

ABSTRACT

A method of connecting elements such as semiconductor devices and a device
5 having connected elements such as semiconductor devices. A first element having a first
contact structure is bonded to a second element having a second contact structure. A
single mask is used to form a via in the first element to expose the first contact and the
second contact. The first contact structure is used as a mask to expose the second contact
structure. A contact member is formed in contact with the first and second contact
10 structures. The first contact structure may have an aperture or gap through which the first
and second contact structures are connected. A back surface of the first contact structure
may be exposed by the etching.